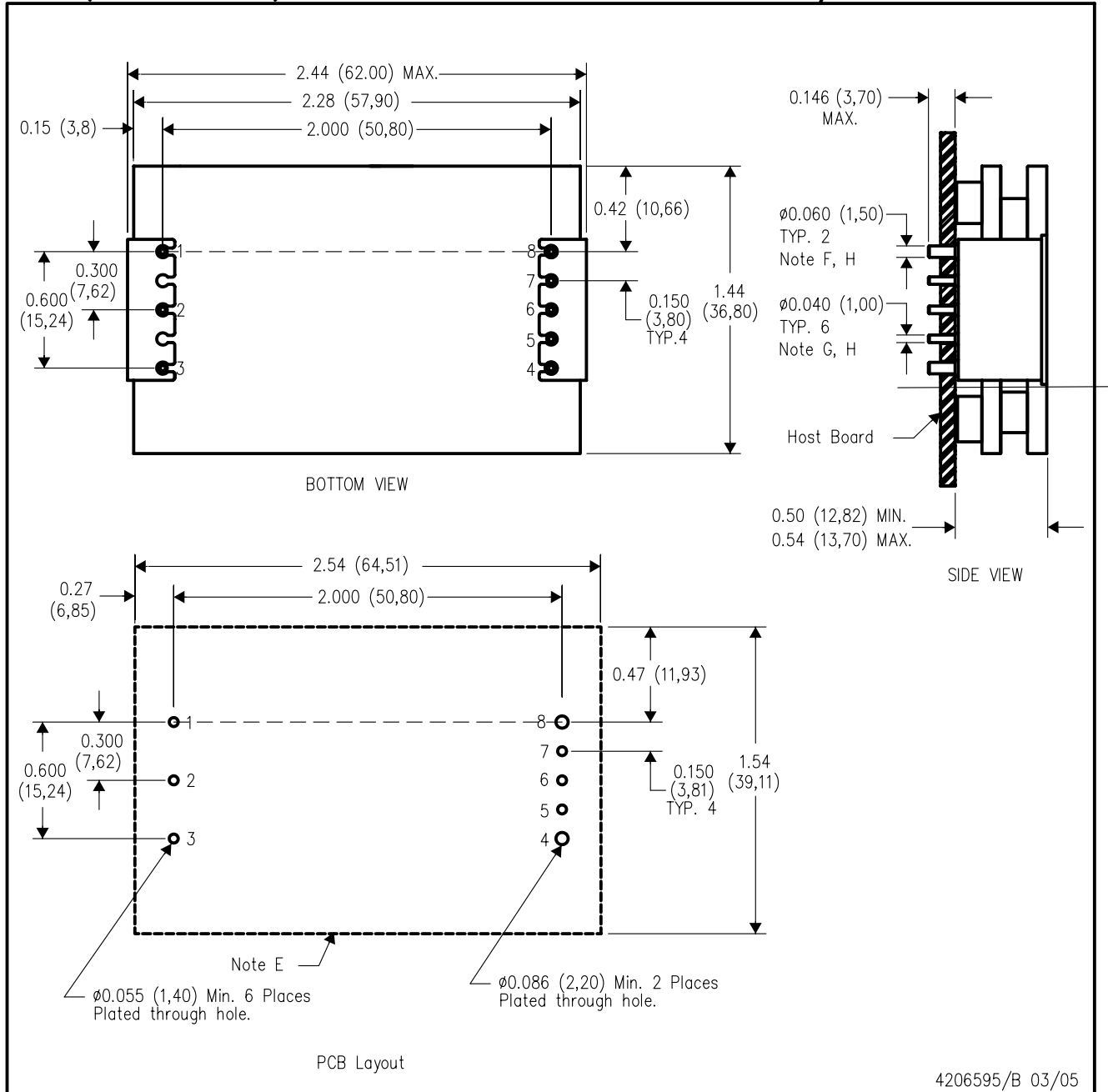


EQF (R-PDSS-T8)

1/4 BRICK MODULE



- NOTES:
- A. All linear dimensions are in inches (mm).
 - B. This drawing is subject to change without notice.
 - C. 2 place decimals are ± 0.020 (± 0.51 mm).
 - D. 3 place decimals are ± 0.010 (± 0.25 mm).
 - E. Recommended keep out area for user components.

- F. Pins are 0.060" (1.50) diameter with 0.125" (3.20) diameter standoff shoulder.
- G. Pins are 0.040" (1.02) diameter.
- H. All pins: Material - Copper Alloy
Finish - Tin (100%) over Nickel plate

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